

VOLENTINE FRANCOS & WHITT, P.L.L.C.
One Freedom Square
11951 Freedom Drive, Suite 1260
Reston, VA 20190 U.S.A.
Tel: 1.571.283.0720
Fax: 1.571.283.0740
Email: iplaw@volentine.com

**FACSIMILE
TRANSMITTAL**

Date: July 1, 2005

**RECEIVED
CENTRAL FAX CENTER**

To: Examiner F. Toledo
U.S. Patent Office

JUL 01 2005

Fax No: 703-872-9306

Ph. No:

From: Andrew J. Telesz, Jr.

Subject: Serial No.: 10/689,936
Our Ref. No.: IIZ.003D2C

No. of Pages (including cover): 9

.....
Comments:

PLEASE CALL IF YOU EXPERIENCE ANY DIFFICULTIES RECEIVING ALL PAGES

PLEASE NOTE that this message is intended for the use of the individual or entity to which it is addressed and may contain information that is privileged, confidential and exempt from disclosure under applicable law. If the reader of the message is not the intended recipient, or the employee or agent responsible for delivering the message to the intended recipient, you are hereby notified that any dissemination, distribution or copying of this communication is strictly prohibited. If you have received this communication in error, please notify us immediately by telephone, and either return the message and any attachments to us at the above address via regular postal service, or destroy the message and any attachments.

CERTIFICATE OF TRANSMISSION BY FACSIMILE (37 CFR 1.8)Applicant(s): **Takashi Ohsumi**

Docket No.

UZ-003D2C

Serial No.
10/689,936Filing Date
October 22, 2003Examiner
F. ToledoGroup Art Unit
2823Invention: **METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS INCLUDING A SEALING MEMBER WITH REDUCED THERMAL STRESS**

I hereby certify that this Letter Submitting Earlier Filed Information Disclosure Statement
(Identify type of correspondence)
is being facsimile transmitted to the United States Patent and Trademark Office (Fax. No. 703-872-9306
on July 1, 2005
(Date)

Andrew J. Telesz, Jr.

(Typed or Printed Name of Person Signing Certificate)

(Signature)

Note: Each paper must have its own certificate of mailing.

Via Facsimile 703-872-9306**IIZ.003D2C****IN THE UNITED STATES PATENT AND TRADEMARK OFFICE****In re PATENT APPLICATION of**

Takashi Ohsumi

Group Art Unit: 2823

**RECEIVED
CENTRAL FAX CENTER**

Serial No.: 10/689,936

Examiner: F. Toledo

JUL 01 2005

Filed: October 22, 2003

Conf. No.: 4027

**FOR: METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS
INCLUDING A SEALING MEMBER WITH REDUCED THERMAL STRESS****LETTER RESUBMITTING EARLIER FILED INFORMATION DISCLOSURE
STATEMENT**

U.S. Patent and Trademark Office
Customer Window, Mail Stop Issue Fee
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Date: July 1, 2005

Sir:

The Notice of Allowability received along with the Notice of Allowance dated June 15, 2005, does not acknowledge receipt of the Information Disclosure Statement filed on April 25, 2005, in connection with the above identified application.

Accordingly, enclosed is a copy of the Information Disclosure Statement and Form PTO/SB/08A form filed on April 25, 2005. Also enclosed is a copy of a dated, stamped postcard receipt provided as evidence that the above noted Information Disclosure Statement was received by the U.S. Patent Office on April 25, 2005.

**Applicant respectfully requests the Examiner to acknowledge that the
Information Disclosure Statement has been received, and to confirm that the**

Serial No.: 10/689,936

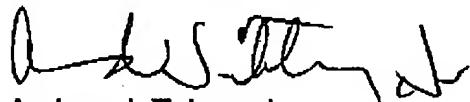
documents will be cited of record.

In the event that there are any outstanding matters remaining in the present application, please contact Andrew J. Telesz, Jr. (Reg. No. 33,581) at (571) 283-0720 in the Washington, D.C. area, to discuss these matters.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment for any additional fees that may be required, or credit any overpayment, to Deposit Account No. 50-0238.

Respectfully submitted,

VOLENTINE FRANCOS & WHITT, P.L.L.C.



Andrew J. Telesz, Jr.
Registration No. 33,581

11951 Freedom Drive, Suite 1260
Reston, Virginia 20190
Telephone No.: (571) 283-0720
Facsimile No.: (571) 283-0740

Enclosures: • Copy of Information Disclosure Statement and PTO/SB/08A form filed on April 25, 2005
• Copy of dated, stamped postcard receipt

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT
 (Under 37 CFR 1.97(b) or 1.97(c))

Docket No.
 IIZ.003D2C

In Re Application Of: **Takashi Ohsumi**

Application No.	Filing Date	Examiner	Customer No.	Group Art Unit	Confirmation No.
10/689,936	October 22, 2003	R. Toledo		2823	4027

Title: A METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS INCLUDING A SEALING MEMBER WITH REDUCED THERMAL STRESS

Address to:
Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

37 CFR 1.97(b)

- The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application other than a continued prosecution application under 37 CFR 1.53(d); within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; before the mailing of a first Office Action on the merits, or before the mailing of a first Office Action after the filing of a request for continued examination under 37 CFR 1.114.

37 CFR 1.97(c)

- The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(b), provided that the Information Disclosure Statement is filed before the mailing date of a Final Action under 37 CFR 1.113, a Notice of Allowance under 37 CFR 1.311, or an Action that otherwise closes prosecution in the application, and is accompanied by one of:

the statement specified in 37 CFR 1.97(e);

OR

the fee set forth in 37 CFR 1.17(p).

Note: The references listed on Form PTO/SB/08A were cited in copending U.S. Application Serial No. 10/957,620, and thus may be material to the prosecution of the present application.

P10A/REV05

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT
 (Under 37 CFR 1.97(b) or 1.97(c))

Docket No.
 IIZ.003.D2C

In Re Application: **Takashi Ohsumi**

Application No.	Filing Date	Examiner	Customer No.	Group Art Unit	Confirmation No.
10/689,936	October 22, 2003	F. Toledo		2823	4027
Title: A METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS INCLUDING A SEALING MEMBER WITH REDUCED THERMAL STRESS					

Payment of Fee

(Only complete if Applicant elects to pay the fee set forth in 37 CFR 1.17(p))

- A check in the amount of _____ is attached.
- The Director is hereby authorized to charge and credit Deposit Account No. 50-0238 as described below.
- Charge the amount of _____
- Credit any overpayment.
- Charge any additional fee required.
- Payment by credit card. Form PTO-2038 is attached.

WARNING: Information on this form may become public. Credit card information should not be included on this form. Provide credit card information and authorization on PTO-2038.

Certificate of Transmission by Facsimile*

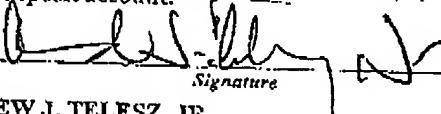
I certify that this document and authorization to charge deposit account is being facsimile transmitted to the United States Patent and Trademark Office (Fax. No. _____)

(Date) _____

Signature _____

Typed or Printed Name of Person Signing Certificate

*This certificate may only be used if paying by deposit account.


 Signature _____

ANDREW J. TELESZ, JR.
 EG. NO. 33,581

Certificate of Mailing by First Class Mail

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)] on _____

(Date) _____

Signature of Person Mailing Correspondence _____

Typed or Printed Name of Person Mailing Certificate

Dated: April 25, 2005

OLVENTINE FRANCOS & WHITT, P.L.L.C.
 NE FREEDOM SQUARE
 1951 FREEDOM DRIVE, SUITE 1260
 ESTON, VA 20190
 EL. NO. (571) 283-0720

P104REV05

**STATEMENT UNDER 37 CFR 1.97(e) ACCOMPANYING
INFORMATION DISCLOSURE STATEMENT**

Docket No.
IIZ.003D2C

In Re Application Of: Takashi Ohsumi

Application No. 10/689,936	Filing Date October 22, 2003	Examiner F. Toledo	Customer No.	Group Art Unit 2823	Confirmation No. 4027
-------------------------------	---------------------------------	-----------------------	--------------	------------------------	--------------------------

Invention: **A METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS INCLUDING A SEALING MEMBER WITH REDUCED THERMAL STRESS**

COMMISSIONER FOR PATENTS:

This is a statement under the provisions of 37 CFR 1.97(e) in the above-identified application.

Check applicable statement herebelow:

Statement Under 37 CFR 1.97(e)(1)

- Each item of information contained in the accompanying Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Information Disclosure Statement.

Statement Under 37 CFR 1.97(e)(2)

- No item of information contained in the accompanying Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the undersigned person, after making reasonable inquiry, no item of information contained in the accompanying Information Disclosure Statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the Information Disclosure Statement.


Signature

Dated: April 25, 2005

ANDREW J. TELESZ, JR.
REG. NO. 33,581

VOLENTE FRANCOS & WHITT, P.L.L.C.
ONE FREEDOM SQUARE
1951 FREEDOM DRIVE, SUITE 1260
WESTON, VA 20190
TEL. NO. (571) 283-0720

Certificate of Mailing by First Class Mail

I certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)] on

(Date)

Signature of Person Mailing Correspondence

Typed or Printed Name of Person Mailing Correspondence

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.
U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE
Approved for use through 07/31/2006, OMB 0651-0031
Substitute for form 1449/PTO
Complete if known

Substitute for form 1449/ETC

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

Use as many sheets as necessary.

Sheet 1 of 1

Complete if Known	
Application Number	10/689,936
Filing Date	October 22, 2003
First Named Inventor	Takashi Ohsumi
Art Unit	2823
Examiner Name	F. Toledo
Attorney Docket Number	11Z 003D2C

U. S. PATENT DOCUMENTS

FOREIGN PATENT DOCUMENTS

Examiner
Signature

Date
Considered

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 809. Draw line through citation if not in conformance and not considered. Induce copy of this form with next communication to applicant. ¹Applicant's unique citation designation number (optional). ²See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. ³Enter Office that issued the document, by the two-letter code (WIPO Standard ST 3). ⁴For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵For the appropriate symbol as indicated on the document under WIPO Standard ST 16 if possible. ⁶Applicant is in charge. ⁷Indicate if translation is attached.

This collection of information is required by 37 CFR 1.97 and 1.98. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 2 hours to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments and Trademark Office, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

If you need assistance in completing the form, call 1-800-PTO-9199 (1-800-786-9199) and select option 2.

ATTY DOCKET #: IIZ.003D20

APPLICANT: Takashi Ohsumi APR 25 2005 DUE DATE:

SERIAL NO.: 10/689,936

FILING DATE: October 22, 2003

TITLE: A METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS
INCLUDING A SEALING MEMBER WITH REDUCED THERMAL
STRESS

RECEIPT OF THE FOLLOWING PAPERS IS ACKNOWLEDGED:

Transmittal of Information Disclosure Statement; Statement Under 37 C.F.R.
1.97(e) Accompanying Information Disclosure Statement; PTO/SB/08A Form;
and Letter of Related Application.

DATE: April 25, 2005

ATTY: AJT

[Check No. N/A]